

RELIABILITY REPORT
FOR
MAX3680EAI+
PLASTIC ENCAPSULATED DEVICES

October 7, 2009

MAXIM INTEGRATED PRODUCTS

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Approved by
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Conclusion

The MAX3680EAI+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

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I. Device Description

A. General

The MAX3680/MAX3680A deserializer is ideal for converting 622Mbps serial data to 8-bit-wide, 77Mbps parallel data in ATM and SDH/SONET applications. Operating from a single +3.3V supply, this device accepts PECL serial clock and data inputs, and delivers TTL clock and data outputs. The MAX3680 also provides a TTL synchronization input that enables data realignment and reframing. The MAX3680/MAX3680A is available in the extended-industrial temperature range (-40°C to +85°C), in a 28-pin SSOP package.

II. Manufacturing Information

A. Description/Function:	+3.3V, 622Mbps, SDH/SONET 1:8 Deserializer with TTL Outputs
B. Process:	GST2
C. Number of Device Transistors:	1346
D. Fabrication Location:	Oregon
E. Assembly Location:	Philippines, Malaysia
F. Date of Initial Production:	April 04, 1997

III. Packaging Information

A. Package Type:	28-pin SSOP
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive Epoxy
E. Bondwire:	Gold (1.3 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-7001-0211
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	120°C/W
K. Single Layer Theta Jc:	26°C/W
L. Multi Layer Theta Ja:	68°C/W
M. Multi Layer Theta Jc:	25°C/W

IV. Die Information

A. Dimensions:	61 X 62 mils
B. Passivation:	Si ₃ N ₄ (Silicon nitride)
C. Interconnect:	Au
D. Backside Metallization:	None
E. Minimum Metal Width:	2 microns (as drawn)
F. Minimum Metal Spacing:	2 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO ₂
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

- A. Quality Assurance Contacts: Ken Wendel (Director, Reliability Engineering)
Bryan Preeshl (Managing Director of QA)
- B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.
0.1% For all Visual Defects.
- C. Observed Outgoing Defect Rate: < 50 ppm
- D. Sampling Plan: Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 150°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 46 \times 2} \text{ (Chi square value for MTTF upper limit)}$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$$\lambda = 10.69 \times 10^{-9}$$

$$\lambda = 10.69 \text{ F.I.T. (60\% confidence level @ 25°C)}$$

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at <http://www.maxim-ic.com/qa/reliability/monitor>. Cumulative monitor data for the GST2 Process results in a FIT Rate of 0.08 @ 25C and 1.42 @ 55C (0.8 eV, 60% UCL)

B. Moisture Resistance Tests

The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

C. E.S.D. and Latch-Up Testing

The HF13 die type has been found to have all pins able to withstand a HBM transient pulse of ±1000V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of ±250mA.

Table 1
Reliability Evaluation Test Results

MAX3680EAI+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES
Static Life Test (Note 1)				
	Ta = 150°C Biased Time = 192 hrs.	DC Parameters & functionality	46	0
Moisture Testing (Note 2)				
HAST	Ta = 130°C RH = 85% Biased Time = 96hrs.	DC Parameters & functionality	77	0
Mechanical Stress (Note 2)				
Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality	77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.

Note 2: Generic Package/Process data